Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L22	13	21 and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 18:23
L21	29	intend$4 with ((reduc$4 or decreas$4) near3 mobility)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 18:23
L20	36	19 and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 18:23
L19	47	prefer$4 with ((reduc$4 or decreas$4) near3 mobility)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 18:23
L18	58	tensile with ((reduc$4 or decreas$4) near3 mobility)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 18:18
L8	12	7 and organic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 18:10
L17	9	pentacene and (thermal adj expansion adj coefficient)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 17:34
L16	0	pentacene same (thermal adj expansion adj coefficient)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 17:34

L13	0	pentacene with (thermal adj expansion adj coefficient)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 17:34
L15	42	(silicon with polymer) with (thermal adj expansion adj coefficient)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 17:24
L14	713	polymer with (thermal adj expansion adj coefficient)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 17:24
L12	220	257/254.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 17:23
L11	263	257/18.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 17:21
L10	9	9 and (mobility with (stress or strain or compressive or tensile))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 17:17
L9	6341	(organic adj semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 16:28
L7	54	6 and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 16:24

L6	170	(compressive and tensile) with (thermal adj expansion adj coefficient)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 16:24
L5	238	(compressive and tensile) with mobility	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 16:23
L4	0	(compressive and tensile) with moblity	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 15:55
L3	0	(compressive and tensile) with mobolity	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 15:55
L2	17	(compressive and tensile) and (organic adj semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 15:55
S11	2	(compressive or tensile) with (organic adj semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 15:42
L1	8	("6437422"|"6452207"|"6603141" |"6631147").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 15:19
S1	2	"20050211973"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 15:18

S17	20	S16 and mobility	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 12:55
S16	170	(compressive and tensile) with (thermal adj expansion adj coefficient)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 12:55
S15	1257	(compressive or tensile) with (thermal adj expansion adj coefficient)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 12:55
S12	4	(compressive or tensile) same (organic adj semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 12:54
S14	3	S13 and (organic with semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 12:52
S13	238	(compressive and tensile) with mobility	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 12:52
S9	1	(compressive or tensile) with mobility with organic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 12:52
S10	4364	(compressive or tensile) with organic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 12:51

S8	5	(stress of strain) with mobility with organic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 12:50
S7	1	(compressive) with mobility with organic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 12:26
S6	1	(compressive and tensile) with mobility with organic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 12:26
S5	238	(compressive and tensile) with mobility	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 12:26
S4	2	S2 and ((stress or strain) with mobility)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 12:25
S3	2	S2 and (stress or strain) with mobility	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 12:25
S2	1863	257/40.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/19 12:24

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      <in>metadata)

#4   ((organic <and> semiconductor <and>
      tensile)<in>metadata)

#5   ((organic <and> semiconductor <and>
      stress)<in>metadata)

#6   ((organic <and> semiconductor <and>
      stress)<in>metadata)

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